



### **Product Summary**

V(BR)DSS	Rds(on)	I <sub>D</sub> T <sub>A</sub> = +25°C
501/	1.8Ω @ V <sub>GS</sub> = 10V	500mA
50V	$2.0\Omega @ V_{GS} = 4.5V$	450mA

## **Description and Applications**

This new generation MOSFET has been designed to minimize the onstate resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

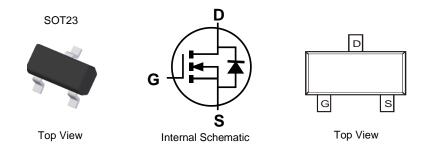
- Backlighting
- **DC-DC Converters**
- **Power Management Functions**

## Low Input/Output Leakage

- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 @3)
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)



### Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BSN20-7	Standard	SOT23	3000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**



N20 = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: G = 2019)

M = Month (ex: 9 = September)

#### Date Code Key

Duie Coue I	(Cy												
Year	2009	-	201	9 20	20 2	021	2022	2023	2024	2025	2026	2027	2028
Code	W	-	G	ŀ	1		J	K	L	М	Ν	0	Р
Mont	h	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Cod	e	1	2	3	4	5	6	7	8	9	0	Ν	D

N-CHANNEL ENHANCEMENT MODE FIELD MOSFET

# **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Charac	teristic		Symbol	Value	Unit
Drain-Source Voltage			VDSS	50	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current @ T <sub>SP</sub> = +25°C (Note 5)	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +100°C	lD	500 300	mA
Pulsed Drain Current @ Tsp = +2	25°C (Notes 5 & 6)		Ідм	1.2	А

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation, $@T_A = +25^{\circ}C$ (Note 5)	PD	600	mW
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 5)	R <sub>θJA</sub>	200	°C/W
Power Dissipation, $@T_{SP} = +25^{\circ}C$ (Note 5)	PD	920	mW
Thermal Resistance, @T <sub>SP</sub> = +25°C (Note 5)	Rejsp	136	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

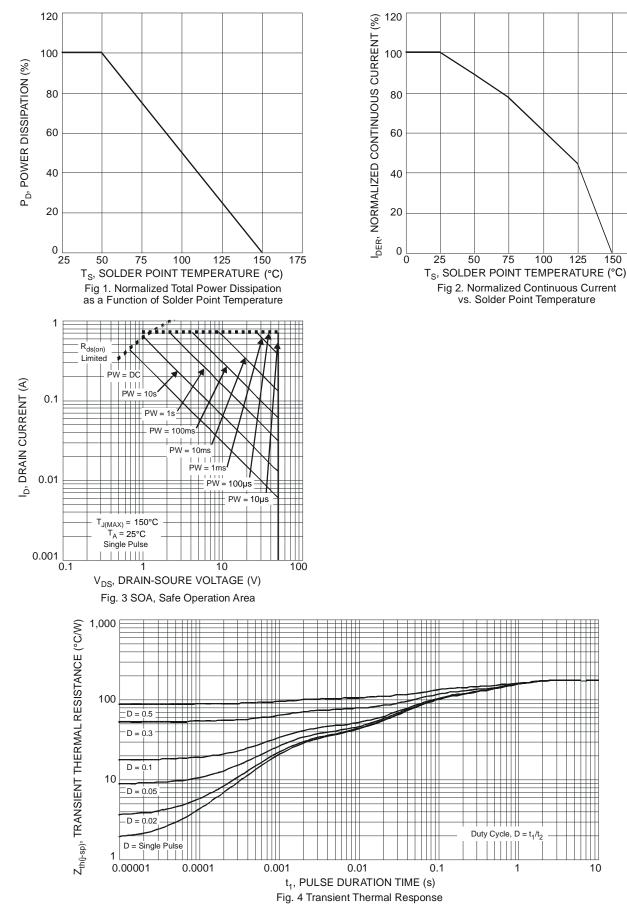
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	50	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current TJ = +25°C	IDSS	_	_	0.5	μA	$V_{DS} = 50V, V_{GS} = 0V$	
Gate-Body Leakage	lgss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(th)	0.4	1.0	1.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	Rds(on)	_	1.3 1.6	1.8 2.0	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.22A V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.1A	
Forward Transfer Admittance	Y <sub>fs</sub>	40	320	—	mS	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.1A	
Diode Forward Voltage	V <sub>SD</sub>	_	1.0	1.5	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 180mA	
Source (Diode Forward) Current	Is		—	194	mA	T <sub>SP</sub> = +25°C	
Peak Source (Diode Forward) Current	I <sub>SM</sub>		—	1.2	А	T <sub>SP</sub> = +25°C	
DYNAMIC CHARACTERISTICS (Note 8)			•	•			
Input Capacitance	Ciss	_	21.8	40	pF	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	5.6	15	pF		
Reverse Transfer Capacitance	Crss	_	3.3	10	pF		
Gate Resistance	Rg	_	49	_	Ω	$V_{DS}$ =0V, $V_{GS}$ = 0V, f = 1MHz	
Total Gate Charge	Qg		800	—	рС		
Gate-Source Charge	Q <sub>gs</sub>		100	_	рС	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 25V, I <sub>D</sub> = 250mA	
Gate-Drain Charge	$Q_{gd}$		100	_	рС		
Turn-On Delay Time	tD(ON)	—	2.93	—	ns		
Turn-On Rise Time	t <sub>R</sub>	_	2.99	—	ns	$V_{DD} = 30V, V_{GEN} = 10V,$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	9.45	—	ns	$R_{L} = 150\Omega, R_{GEN} = 50\Omega,$ $I_{D} = 0.2A$	
Turn-Off Fall Time	tF	_	8.3	_	ns		

 Device mounted on FR-4 PCB, with minimum recommended pad layout.
Repetitive rating, pulse width limited by junction temperature.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to production testing. Notes:

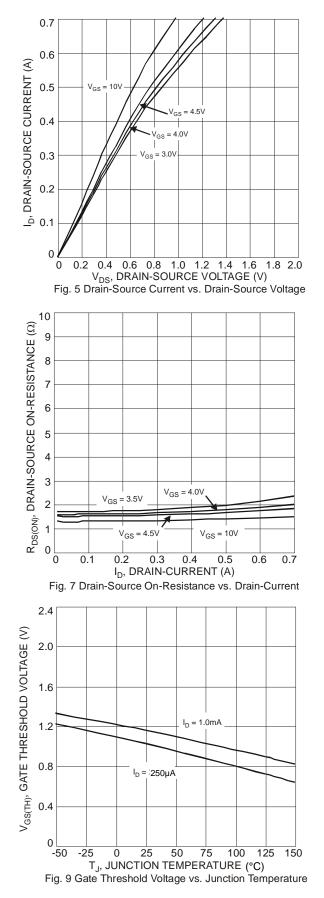


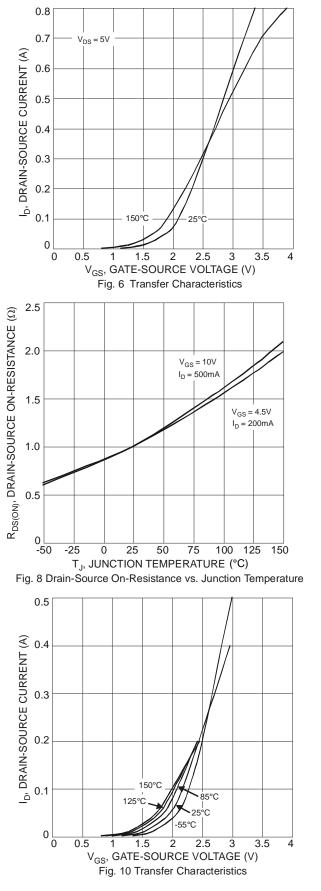
150

175

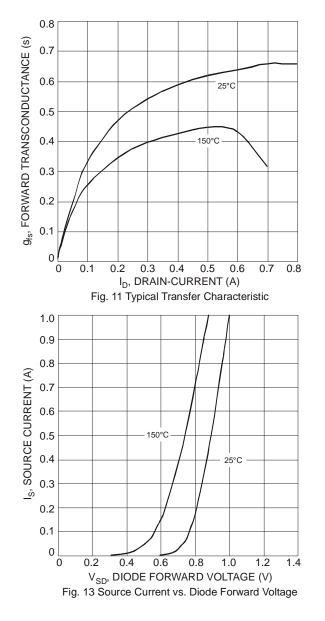


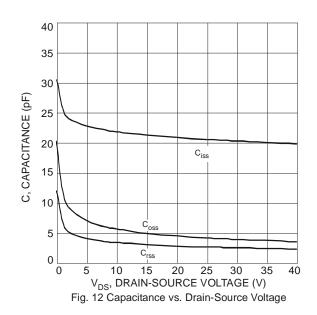








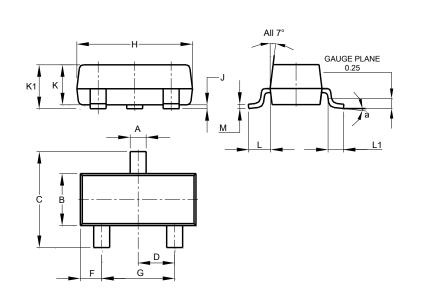






### **Package Outline Dimensions**

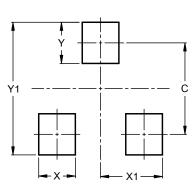
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
c	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All	All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23

SOT23

Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



#### IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2019, Diodes Incorporated

www.diodes.com